

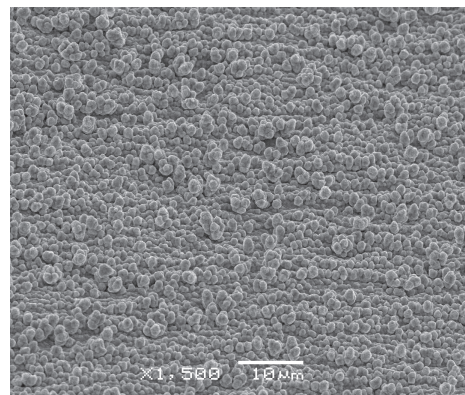
Reverse treat electrodeposited copper foil.

**Applications:**

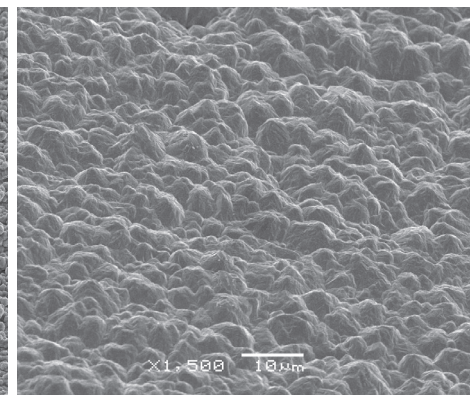
- PCB inner layers

**Features:**

- IPC Grade III
- Treatment on drum side of foil
- Excellent adhesion to a wide range of resin systems



Treated Drum Side  
H oz. /18 µm (1500x)



Untreated Matte Side  
H oz. /18 µm (1500x)

**Typical Values:**

Attribute		Unit	Value						Reference
Thickness Designation			Q	T	H	1	2	3	IPC-4562, 1.2.5.1 Table 1-1; IPC-TM-650-2.2.12
Nominal Thickness		µm	9	12	18	35	70	103	
		oz.	1/4	3/8	1/2	1	2	3	
Area Weight		g/m <sup>2</sup>	75.9	106.8	152.5	305	610	915	
		g/254 in <sup>2</sup>	12.5	17.5	25	50	100	150	
		oz./ft <sup>2</sup>	0.25	0.375	0.5	1	2	3	
Roughness	Drum Side	µm	3.0						IPC-TM-650-2.2.17
		µ"	120						
	Matte Side	µm	2.5	3.2	4.5	5.7	8.9	14.5	
		µ"	100	125	175	225	350	570	
Tensile	Ambient	Kg/mm <sup>2</sup>	42			38.7	36.9	34.7	IPC-TM-650-2.4.18
		Kpsi	60			55	52.5	49.3	
	180°C	Kg/mm <sup>2</sup>	21						
		Kpsi	30						
Elongation	Ambient	%	>3	6	8	15	20	25.5	
	180°C	%	8						
Peel Strength* (Drum/Treated Side)	Cond. B	Kg/cm	>0.89	1.07	1.07	1.42	1.96	2.5	IPC-TM-650-2.4.8
		Lbs/in	>5.0	6	6	8	11	14	

\* Peel strength measured on 170°C Tg Epoxy

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